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1PS76SB10,115

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1PS76SB10

Schottky barrier single diode

18 July 2012 **Product data sheet**

1. Product profile

1.1 General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a SOD323 very small Surface-Mounted Device (SMD) plastic package.

1.2 Features and benefits

- Low forward voltage
- Guard ring protected
- Very small plastic SMD package
- AEC-Q101 qualified

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes

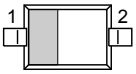
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current			-	-	200	mA
V_R	reverse voltage			-	-	30	V
V_F	forward voltage	I_F = 10 mA; T_{amb} = 25 °C		-	-	400	mV

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SOD323	 aaa-003679
2	A	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
1PS76SB10	SOD323	plastic surface-mounted package; 2 leads	SOD323

4. Marking

Table 4. Marking codes

Type number	Marking code
1PS76SB10	S0

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage			-	30	V
I_F	forward current			-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$		-	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10$ ms; $T_{j(init)} = 25$ °C		-	600	mA
T_j	junction temperature			-	125	°C
T_{amb}	ambient temperature			-65	150	°C
T_{stg}	storage temperature			-65	150	°C

6. Thermal characteristics

Table 6. Thermal characteristics

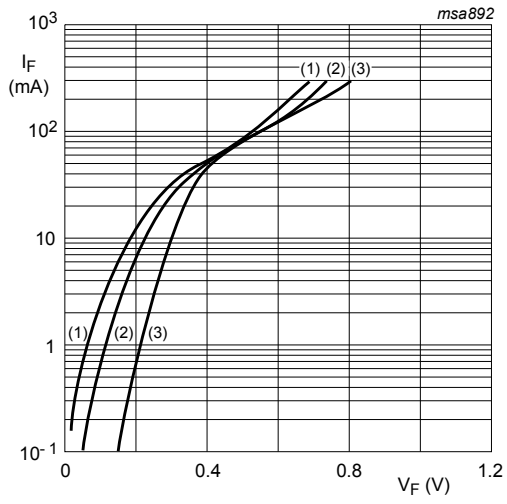
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	450	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

7. Characteristics

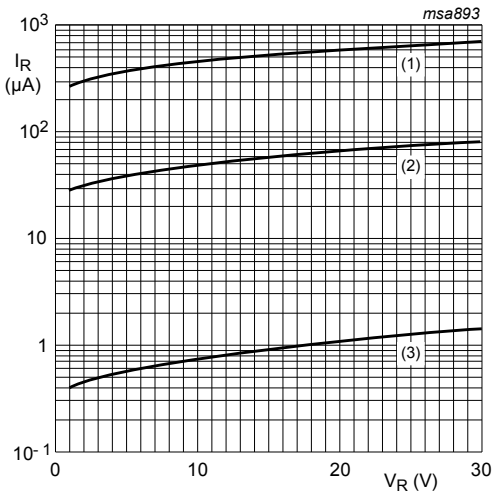
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	I_F = 0.1 mA; T_{amb} = 25 °C		-	-	240	mV
		I_F = 1 mA; T_{amb} = 25 °C		-	-	320	mV
		I_F = 10 mA; T_{amb} = 25 °C		-	-	400	mV
		I_F = 30 mA; T_{amb} = 25 °C		-	-	500	mV
		I_F = 100 mA; T_{amb} = 25 °C		-	-	800	mV
I_R	reverse current	V_R = 25 V; T_{amb} = 25 °C; pulsed; t_p = 300 µs; δ = 0.02		-	-	2	µA
C_d	diode capacitance	f = 1 MHz; T_{amb} = 25 °C; V_R = 1 V		-	-	10	pF



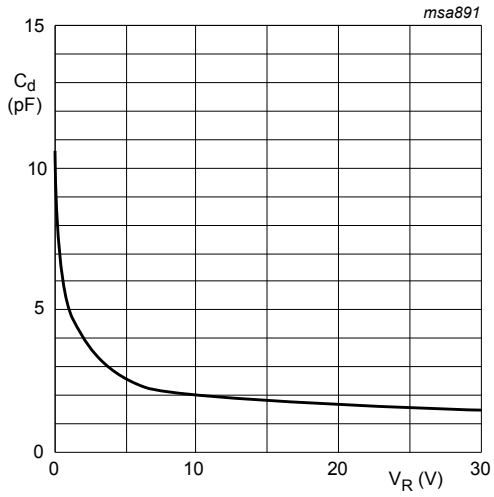
(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig. 1. Forward current as a function of forward voltage; typical values



(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig. 2. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig. 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

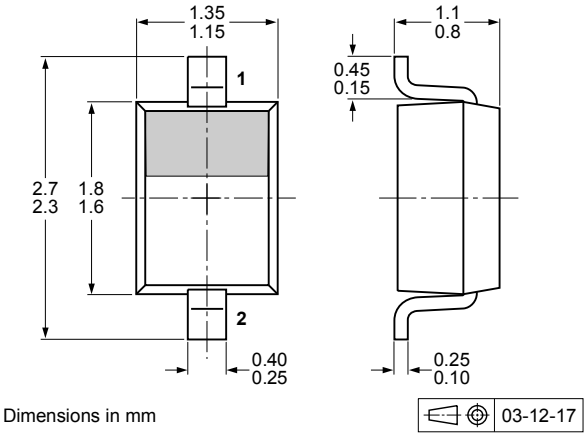


Fig. 4. SOD323

10. Soldering

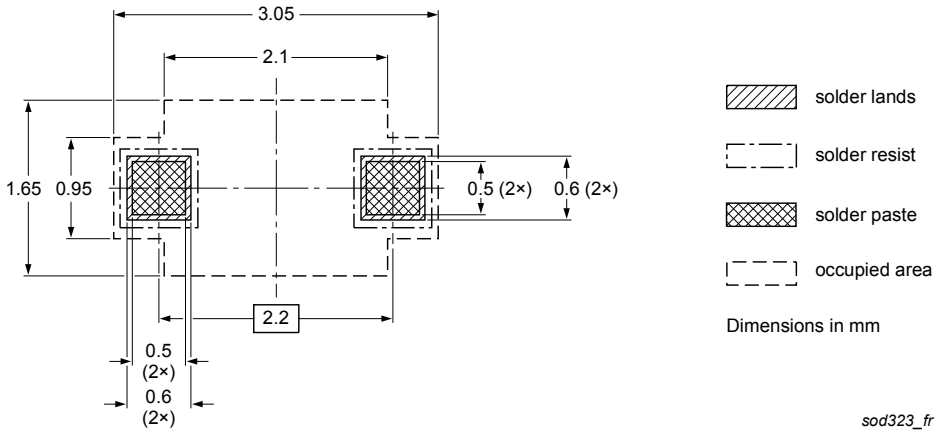


Fig. 5. Reflow soldering footprint for SOD323 (SOD323)

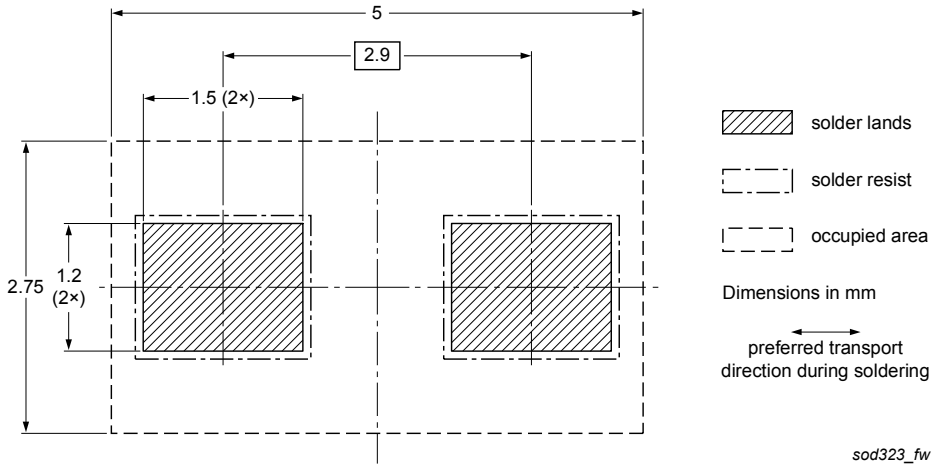


Fig. 6. Wave soldering footprint for SOD323 (SOD323)

11. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
1PS76SB10 v.3	20120718	Product data sheet	-	1PS76SB10 v.2
Modifications:	• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package outline drawing replaced by minimized package ouline drawing • Section "Test information" added • Section "Soldering" added			
1PS76SB10 v.2	20040126	Product specification	-	1PS76SB10 v.1
1PS76SB10 v.1	19961014	Product specification	-	-

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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